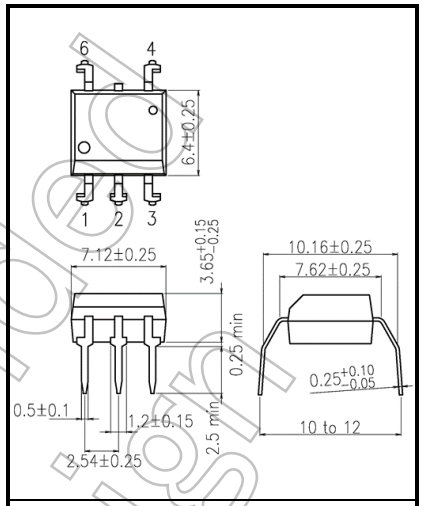
TLP3061F(S),TLP3062F(S),TLP3063F(S)

Unit: mm

OFFICE MACHINE
HOUSEHOLD USE EQUIPMENT
TRIAC DRIVER
SOLID STATE RELAY



JEDEC	—
JEITA	—
TOSHIBA	11-7A902S

weight: 0.39g (typ.)

The TOSHIBA TLP3061F(S), TLP3062F(S), TLP3063F(S) consist of a zero voltage crossing turn-on photo-triac optically coupled to an infrared emitting diode in a six lead plastic DIP package.

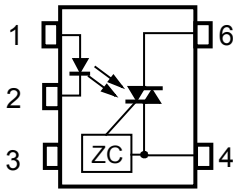
- Peak Off-State Voltage : 600 V (min)
- Trigger LED Current : 15 mA (max) (TLP3061F(S))
  10 mA (max) (TLP3062F(S))
  5 mA (max) (TLP3063F(S))
- On-State Current : 100 mA (max)
- Isolation Voltage : 5000 Vrms (min)
- UL-recognized : UL 1577, File No.E67349
- cUL-recognized : CSA Component Acceptance Service No.5A
  File No.E67349
- CQC-approved : GB4943.1,GB8898 Japan Factory
- VDE-approved : EN 60747-5-5, EN 62368-1 (Note1)

Note 1 : When a VDE approved type is needed,
please designate the **Option (D4)**.

- Construction mechanical rating

	10.16 mm pitch TLPxxxxF type
Creepage Distance	8.0 mm (Min)
Clearance	8.0 mm (Min)
Insulation Thickness	0.5 mm (Min)

Pin Configuration (top view)



1: Anode
2: Cathode
3: N.C.
4:Terminal 1
6:Terminal 2

ZC:Zero-cross Circuit

Start of commercial production
1996-09

Absolute Maximum Ratings (Ta = 25°C)

Characteristic			Symbol	Rating	Unit
LED	Forward current		I_F	50	mA
	Forward current derating (Ta ≥ 53°C)		ΔI_F / °C	−0.7	mA / °C
	Peak forward current (100 μs pulse, 100 pps)		I_{FP}	1	A
	Power dissipation		P_D	100	mW
	Power dissipation derating (Ta ≥ 53°C)		ΔP_D / °C	−1.4	mW / °C
	Reverse voltage		V_R	5	V
	Junction temperature		T_j	125	°C
Detector	Off−state output terminal voltage		V_{DRM}	600	V
	On−state RMS current	Ta = 25°C	$I_{T(RMS)}$	100	mA
		Ta = 70°C		50	
	On−state current derating (Ta ≥ 25°C)		ΔI_T / °C	−1.1	mA / °C
	Peak on−state current (100μs pulse, 120 pps)		I_{TP}	2	A
	Peak nonrepetitive surge current (P_W = 10 ms)		I_{TSM}	1.2	A
	Power dissipation		P_D	300	mW
	Power dissipation derating (Ta ≥ 25°C)		ΔP_D / °C	−4.0	mW / °C
	Junction temperature		T_j	115	°C
Storage temperature range			T_{stg}	−55 to 150	°C
Operating temperature range			T_{opr}	−40 to 100	°C
Lead soldering temperature (10 s)			T_{sol}	260	°C
Total package power dissipation			P_T	330	mW
Total package power dissipation derating (Ta ≥ 25°C)			ΔP_T / °C	−4.4	mW / °C
Isolation voltage (AC, 60 s., R.H.≤ 60 %)		(Note 1)	BV_S	5000	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/“Derating Concept and Methods”) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

(Note 1) Device considered a two terminal device: Pins 1, 2 and 3 shorted together and pins 4 and 6 shorted together.

Recommended Operating Conditions

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Supply voltage	V_{AC}	—	—	240	Vac
Forward current	I_F*	15	20	25	mA
Peak on−state current	I_{TP}	—	—	1	A
Operating temperature	T_{opr}	−25	—	85	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

* In the case of TLP3062

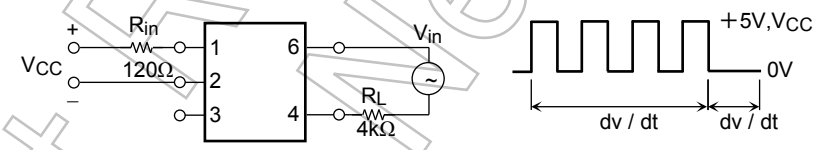
Individual Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min.	Typ.	Max.	Unit
LED	Forward voltage	V_F	I_F = 10 mA	1.0	1.15	1.3	V
	Reverse current	I_R	V_R = 5 V	—	—	10	μA
	Capacitance	C_T	V = 0 V, f = 1 MHz	—	10	—	pF
Detector	Peak off−state current	I_{DRM}	V_{DRM} = 600 V	—	10	1000	nA
	Peak on−state voltage	V_{TM}	I_{TM} = 100 mA	—	1.7	3.0	V
	Holding current	I_H	—	—	0.6	—	mA
	Critical rate of rise of off−state voltage	dv / dt	V_{in} = 240 Vrms, Ta = 85 °C (Fig.1)	200	500	—	V / μs
	Critical rate of rise of commutating voltage	dv / dt (c)	V_{in} = 60 Vrms, I_T = 15 mA (Fig.1)	—	0.2	—	V / μs

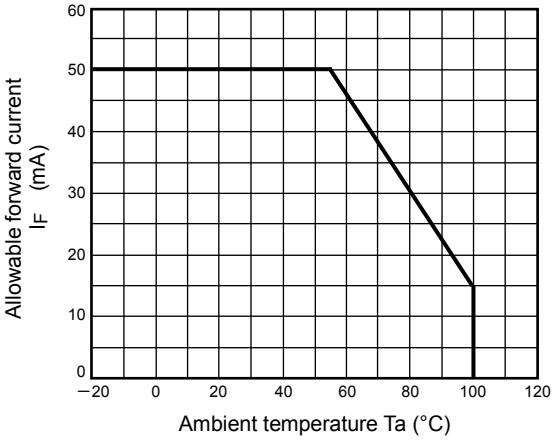
Coupled Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min.	Typ.	Max.	Unit
Trigger LED current	TLP3061F(S)	I_{FT}	V_T = 3 V	—	—	15	mA
	TLP3062F(S)			—	5	10	
	TLP3063F(S)			—	—	5	
Inhibit voltage		V_{IH}	I_F = rated I_{FT}	—	—	50	V
Leakage in inhibited state		I_{IH}	I_F = rated I_{FT}, V_T = rated V_{DRM}	—	100	300	μA
Capacitance input to output		C_S	V_S = 0 V, f = 1 MHz	—	0.8	—	pF
Isolation resistance		R_S	V_S = 500 V , R.H.≤ 60 %	5×10^{10}	10^{14}	—	Ω
Isolation voltage		BV_S	AC, 60 s	5000	—	—	Vrms

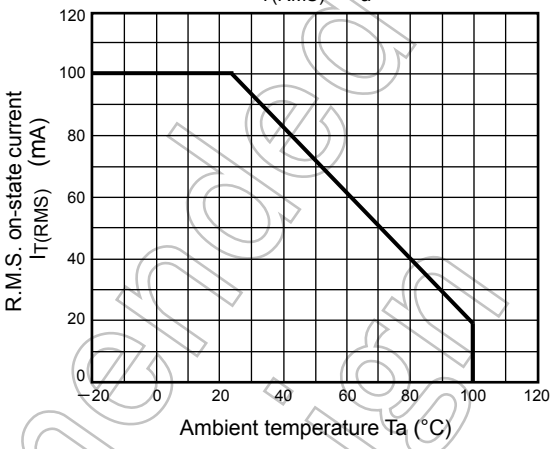
Fig. 1 dv / dt test circuit



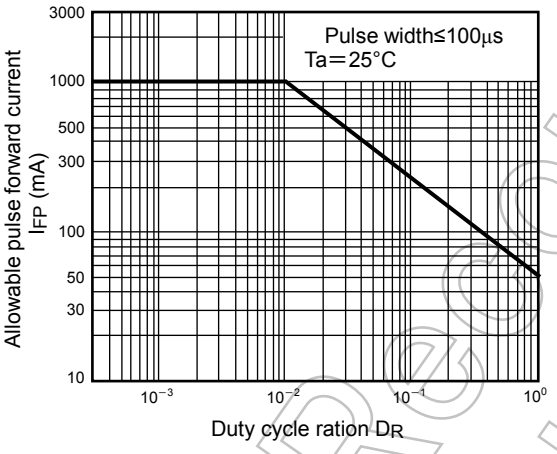
$I_F - T_a$



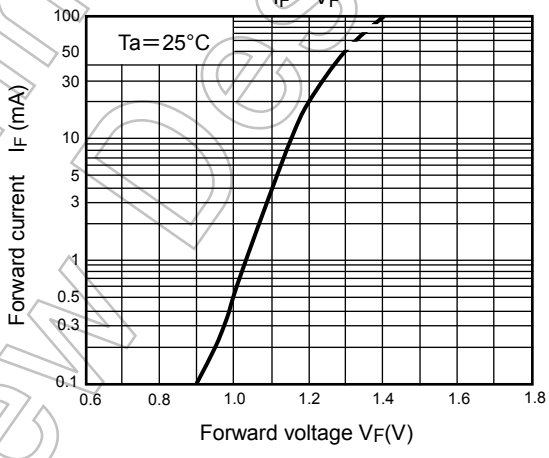
$I_{T(RMS)} - T_a$



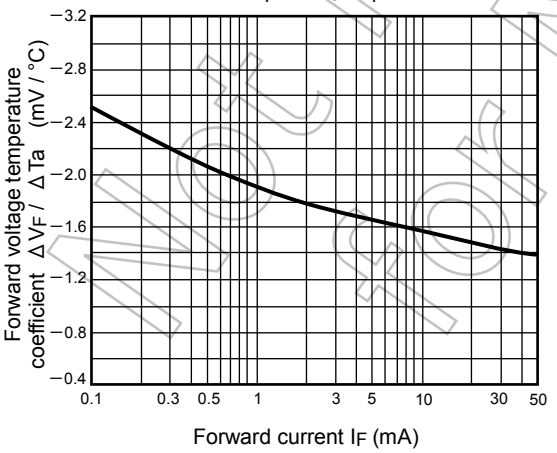
$I_{FP} - D_R$



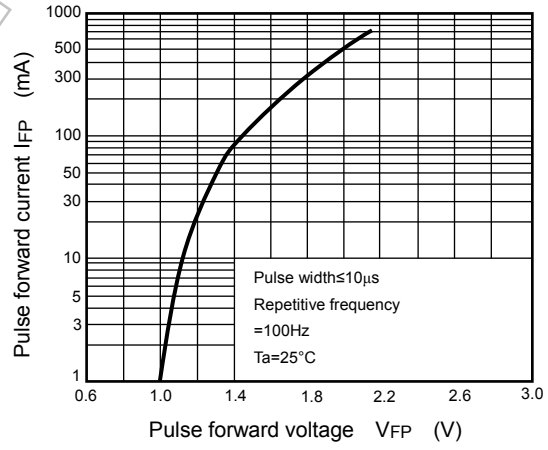
$I_F - V_F$



$\Delta V_F / \Delta Ta - I_F$

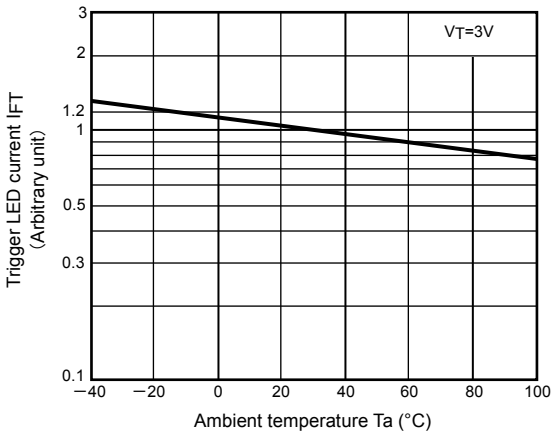


$I_{FP} - V_{FP}$

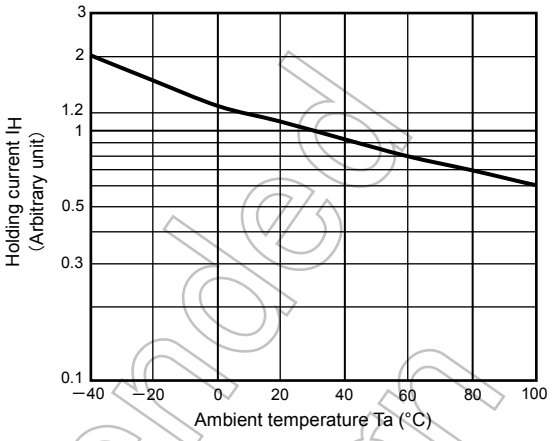


NOTE: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

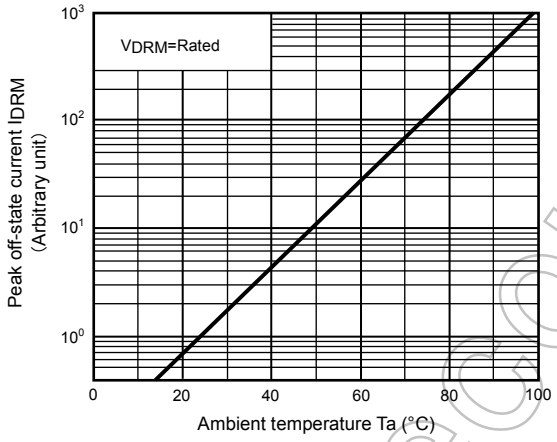
Normalized I_{FT} — Ta



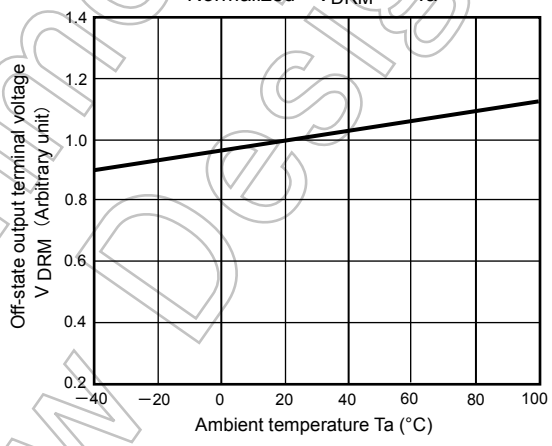
Normalized I_H — Ta



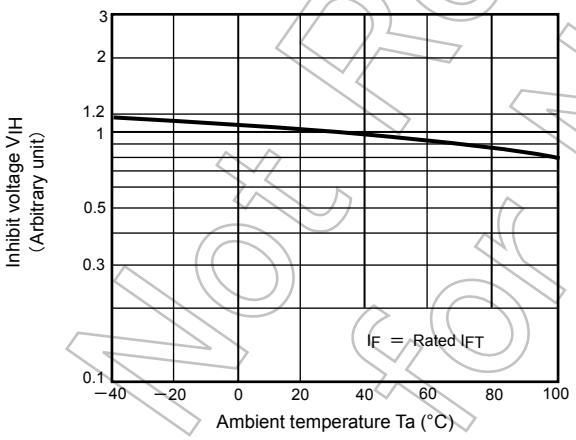
Normalized I_{DRM} — Ta



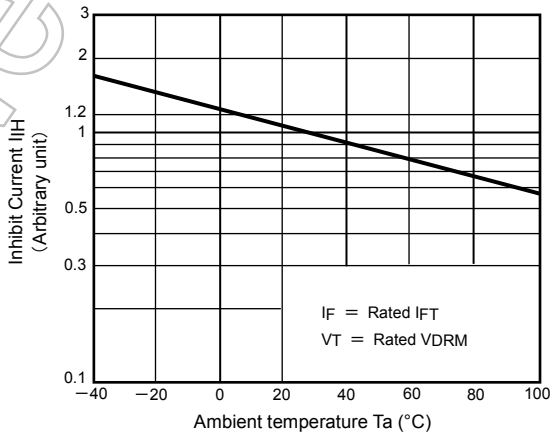
Normalized V_{DRM} — Ta



Normalized V_{IH} — Ta



Normalized I_{IH} — Ta



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